



PATENT

YO996-184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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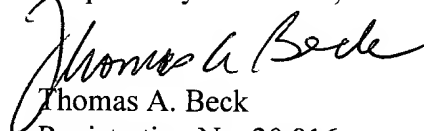
In re Application of : D.Y.Shih, et al.  
Serial Number : 09/254,769  
Filing Date : March 11, 1999  
Examiner : V. Nguyen  
Group Art Unit : 2858  
For :  
WAFER SCALE HIGH DENSITY  
PROBE ASSEMBLY,  
APPARATUS FOR USE THEREOF  
AND METHODS OF  
FABRICATION THEREOF

Honorable Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

Sir:

Applicants respectfully file this response to the Official Action dated December 7, 2000 wherein the Examiner requested submission of an Abstract of the Disclosure. A response to the substantive issues raised in the Official Action is being filed concurrently.

Respectfully Submitted,



Thomas A. Beck  
Registration No. 20,816  
26 Rockledge Lane  
New Milford, CT 06776  
Telephone (860) 354-0892

I hereby certify that this paper is being transmitted by First Class mail addressed to Commissioner of Patents & Trademarks, Washington, D.C. 20231

Signature:   
Name: Thomas A. Beck

Date: April 07, 2001